

# Tin Whiskers

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Tin whiskers—spontaneously growing crystalline structures on tin surfaces—pose a significant risk to the reliability and functionality of electronic devices, especially as they cause short circuits and component failures. This presentation will provide an overview of the PbSn plating process used to mitigate tin whisker formation. Examples of the potential consequences for modern electronics, and alternate mitigation strategies. In addition, we will explore emerging technologies and industry standards aimed at minimizing the occurrence and impact of tin whiskers in critical applications.